PRODUCT ADVANTAGE

- Fast Flow at Room Temperature
- Enhanced Mechanical Resistance
- High Reliability
- Flows Freely into Small Gaps
- No Voids
- No Phase Separation
- Minimized Induced Stress

OUR THREE PILLARS

1. EXCEEDING PERFORMANCE SPECIFICATIONS
2. MAXIMIZING PRODUCTIVITY
3. LOWERING PROCESS COST

YINCAE Advanced Materials, LLC
19 Walker Way
Albany, NY 12205 USA
(518) 452-2880
www.yincae.com

Worldwide Service and Sales Organization
info@yincae.com

YPB-005 (Version 5/2017)

YINCAE®

INNOVATION AT ITS BEST

SMT 158UL Series

Fast Room Temperature Flow Capillary Underfill

Preferred by global leaders in the electronics manufacturing industry

YINCAE® SMT 158UL Series Underfill Materials

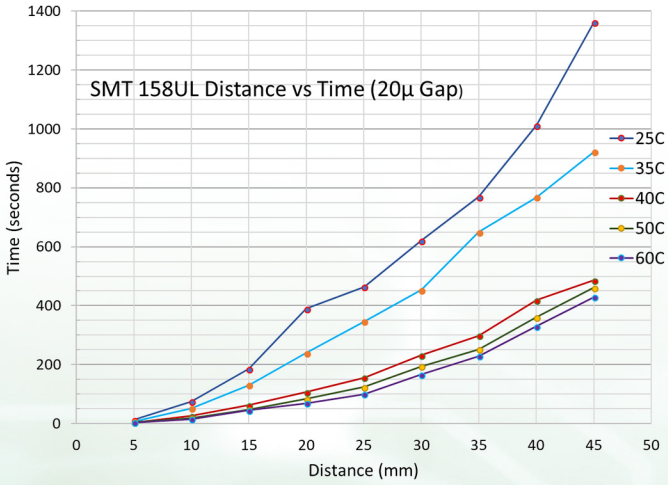
SMT 158UL is a room temperature fast flow filled underfill material. It does not require substrate heating to flow freely into gaps as small as 10µm. SMT 158UL can cure as fast as 15 minutes at 150°C without void formation or phase separation. It is also available in a UV curable formula, SMT 158UV, for heat sensitive applications.

SMT 88UL is the unfilled version of SMT 158UL. It was created in response to demands for a room temperature fast flow underfill that can flow freely into gaps as small as 1µm. For thermally sensitive applications, the UV curable SMT 88UV is also available.

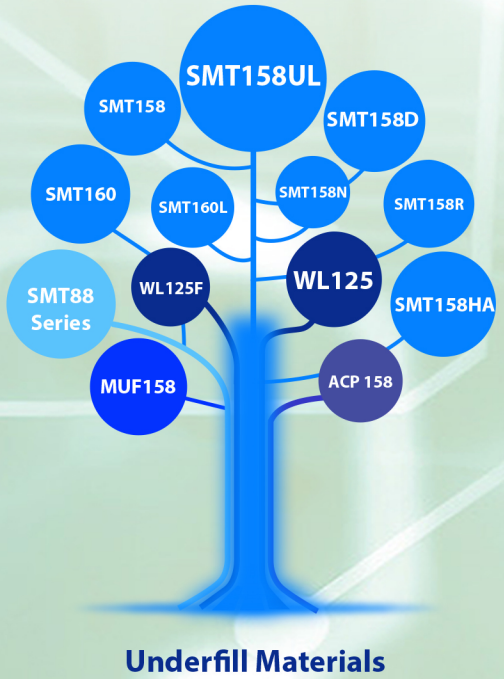
Highly Filled Room Temperature Fast Flow Underfill SMT 158UL

TYPICAL PHYSICAL PROPERTIES

Product Name	SMT 158UL Underfill
PROPERTIES OF UNCURED MATERIAL	
Appearance	White
Specific Gravity (ASTM D 1475-60)	1.45 – 1.55 g/cc
Viscosity (Brookfield, 0.5 rpm)	70-150 cp
PROPERTIES OF CURED MATERIAL	
Glass Transition Temperature (Tg) Via TMA (ASTM D3418-82)	100 – 110 °C
C.T. E (ASTM E 831), PPM /°C	α1 = 35; α2 = 162
Lap Shear Strength (FR4/FR4)	2600 psi
Extractable ions (MIL-STD-883E)	
Na+	<5ppm
K+	<5ppm
F-	<5ppm
Cl-	<10ppm
Surface insulation resistance (J-STD-004)	Pass



SMT 158UL shows an excellent flow rate at room temperature.



Contact YINCAE at info@yincae.com for detailed specifications & customization for your specific product requirements.